

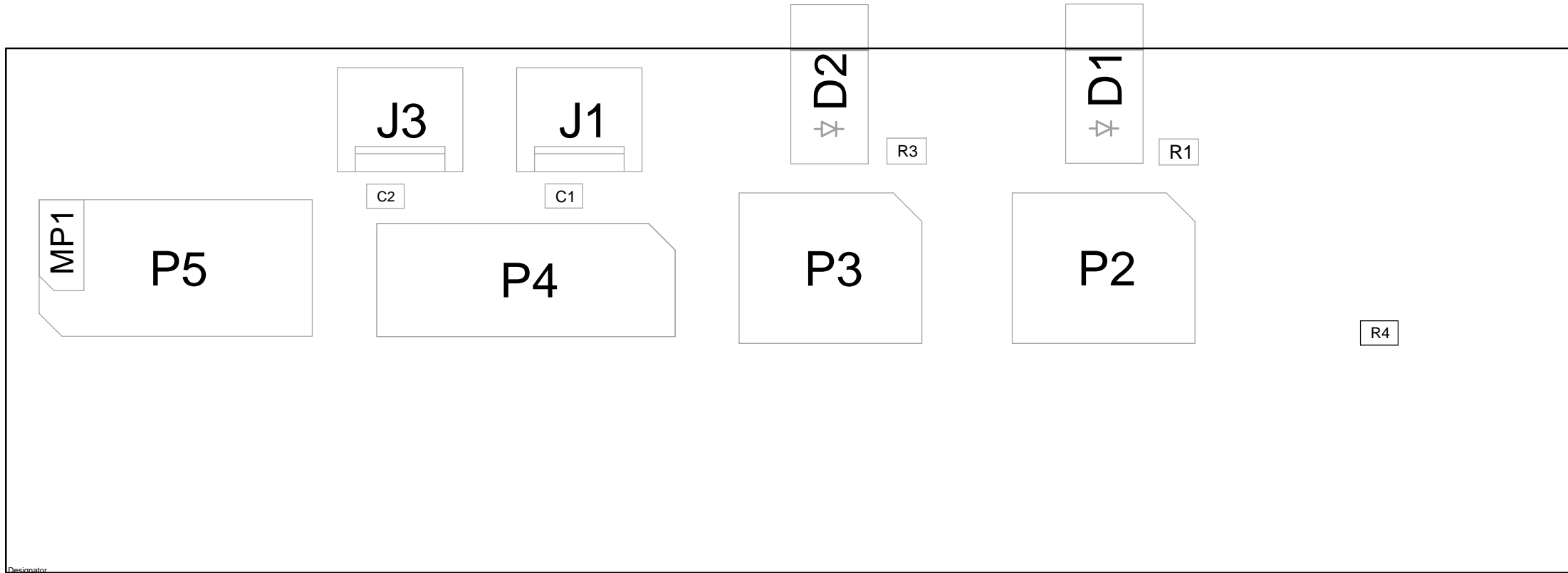
MTCA-Bringup-Adapter

Production Information

Board Thickness: 1.60mm
Layer Count: 4
Layer Stackup: 'Leiton 4-Layer Multilayer 1,60mm 35um/35um
 aus DEUTSCHER Fertigung'

Board Material: Panasonic R1566W, TG150
Structure Size: 125um
Smallest Hole: 300 um
Surface: NiAu
Print Overlay (Silkscreen): top and bottom
Board Outline: Milled
PCIe Impedances: 90R diff. GCPW 125/210/125/210/125, top layer only
 PCIe needs correct 90R impedances and low-loss material.
 Adhere to the given stackup and material.
 If stackup or material deviatges, trace geometries
 need to be modified and checked.

Via plugging: no
Solder Stop: green



Layer Legend

Template / Board Information
Board Outline

Assembly Drawing

Top Component Outlines
Top Designators

Stackup Definition

L1	solder mask	15 um
		35 um
L2	2x 7628 prepreg	378 um
		35 um
L3	FR4 core	710 um
		35 um
L4	2x 7628 prepreg	378 um
		35 um
	solder mask	15 um

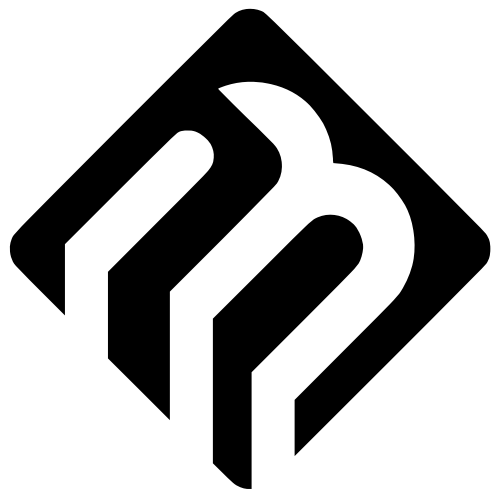
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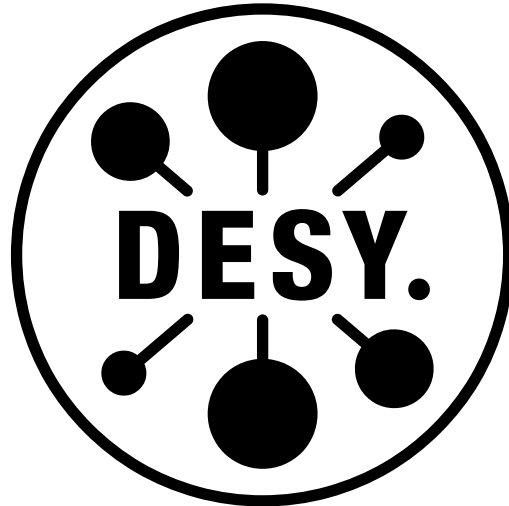
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microTCA
TECHNOLOGY LAB



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DATE:
20.12.2023

FILE NAME:
bringup-adapter.pcbdoc

PROJECT TITLE:
MTCA-Bringup-Adapter
Top Layer Designators

LP NO.:
-

LP Type:
6 Layers

REV: **B**

SCALE:
SCALE: 1.00

A

B

C

D

A

B

D

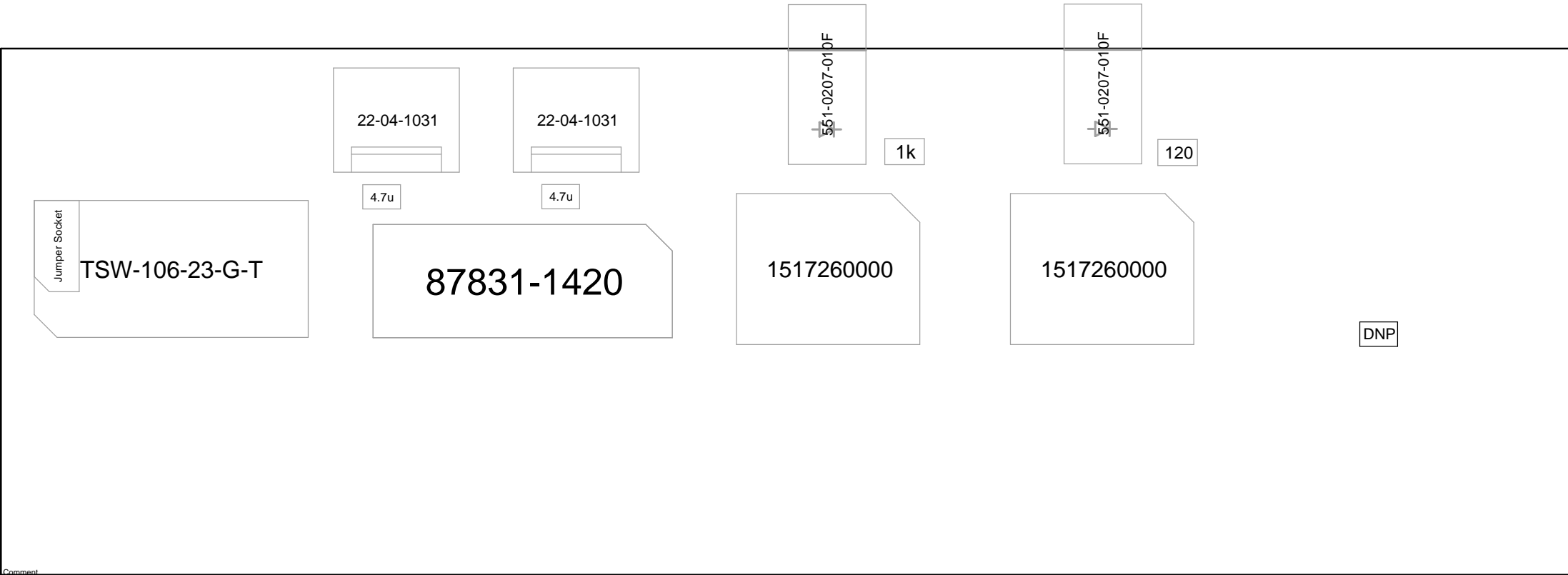
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 need to be modified and checked.

Via plugging: no
Solder Stop: green



Layer Legend

Template / Board Information
Board Outline

Assembly Drawing

Top Component Outlines

Top Values

Stackup Definition

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		35 um
L2	2x 7628 prepreg	378 um
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L4	2x 7628 prepreg	378 um
		35 um
	solder mask	15 um

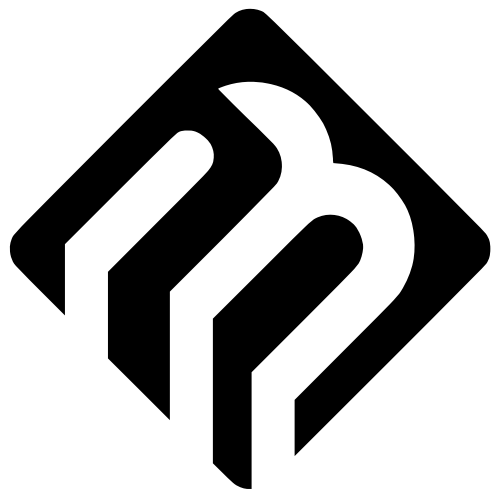
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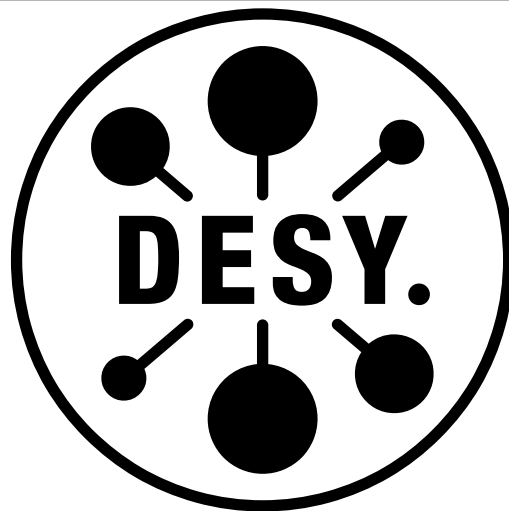
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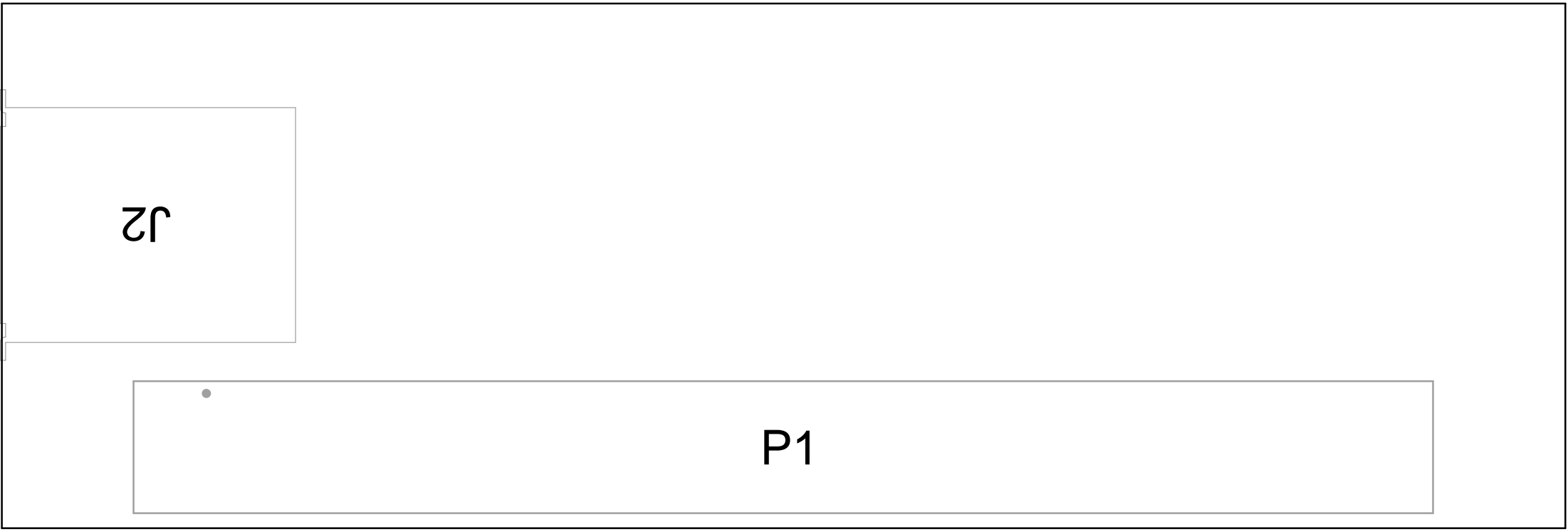
Top Layer Values

LP NO.:
-

LP Type:
6 Layers

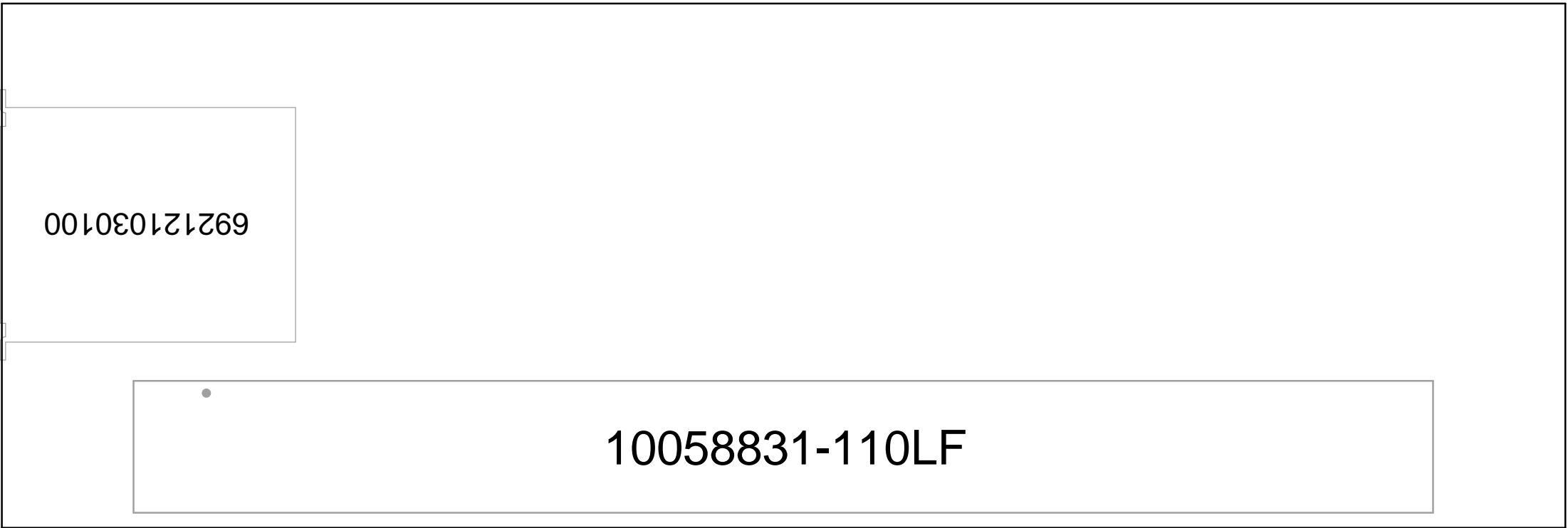
REV: **B**

SCALE:
SCALE: 1.00



Bottom Designators
Bottom Component Outlines

Board Outline



Board Outline

Bottom Values
Bottom Component Outlines